

NOMENCLATURE

- $a_1, a_2, a_3 \dots$ displacement coefficients defined in two-dimensional analysis, in, in, dimensionless
- $a_5, a_6 \dots \dots$ displacement coefficients defined in one-dimensional analysis, in, dimensionless
- $a_7 \dots \dots \dots$ displacement coefficient defined in rigid-anvil analysis, dimensionless
- $b \dots \dots \dots$ characteristic measure of wafer material strain hardening, psi
- $D \dots \dots \dots$ initial wafer diameter, in
- $\dot{E}' \dots \dots \dots$ deviator strain rate tensor, sec⁻¹
- $E'' \dots \dots \dots$ spherical strain tensor, in/in
- $f \dots \dots \dots$ coefficient of friction
- $F \dots \dots \dots$ applied compressive force, lbs
- $G \dots \dots \dots$ shearing modulus of wafer material, psi
- $2h_c \dots \dots \dots$ wafer height measured along axis of revolution, in
- $2h_o \dots \dots \dots$ original wafer centerline height, in
- $H \dots \dots \dots$ initial wafer height, in
- $n \dots \dots \dots$ characteristic curvature of plastic strain hardening of wafer material in one-dimensional analysis
- $P_1 \dots \dots \dots$ constraining pressure attributed to radial constraints, psi
- $P_c \dots \dots \dots$ constraining pressure at mid-meridian plane, psi
- $r, \theta, z \dots \dots \dots$ radial, circumferential, and tangential coordinates, in, rad, in
- $R_o \dots \dots \dots$ initial wafer radius, in
- $R \dots \dots \dots$ current wafer radius, in